

NVRAMOS 2010 Spring

Wear Leveling for TLC NAND Flash

April 19, 2010

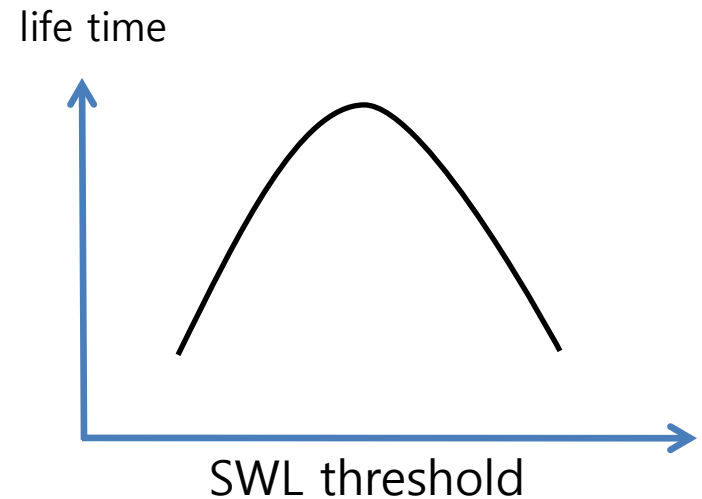
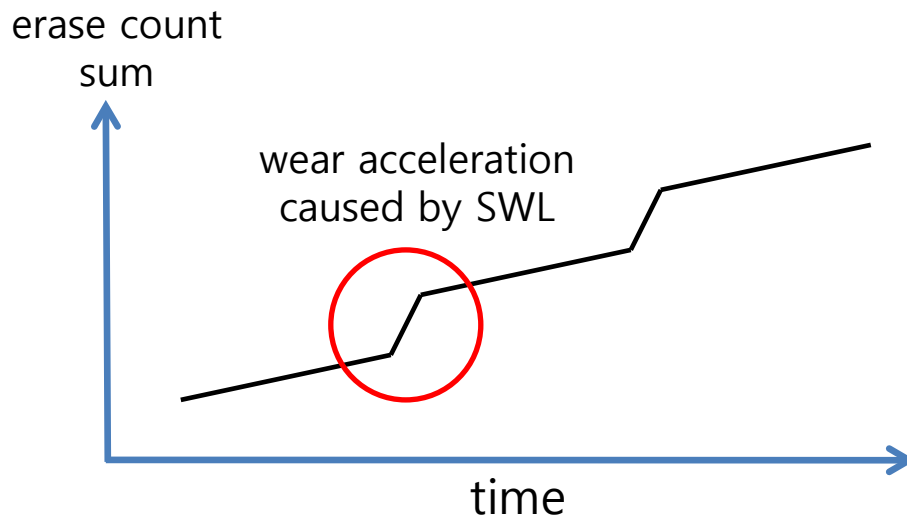
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Agenda

- Impact of Static Wear Leveling
- Impact of Over Provisioning
- Impact of Global Wear Leveling
- Miscellaneous Issues

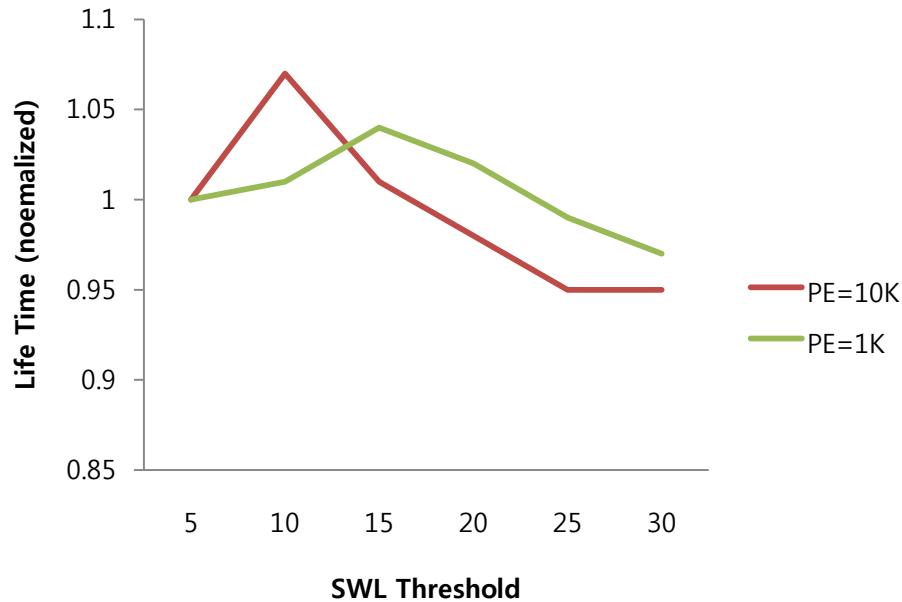
Impact of Static Wear Leveling

- Static Wear Leveling (SWL)
 - Cold data are copied from young blocks to older so that those young blocks can be erased and written to.
 - This copy actions contribute to wear acceleration.
 - Narrow distribution of erase counts should not trigger static wear leveling.
 - Ultimate purpose of Wear Leveling is not to even out erase counts, but to prolong the life time.



SWL Threshold for TLC

- Increase of total erase count caused by SWL
 - It gets more expensive as PE cycle limit becomes lower.
 - **Variance of erase counts should be tolerated to a larger point.**
- Simulation result



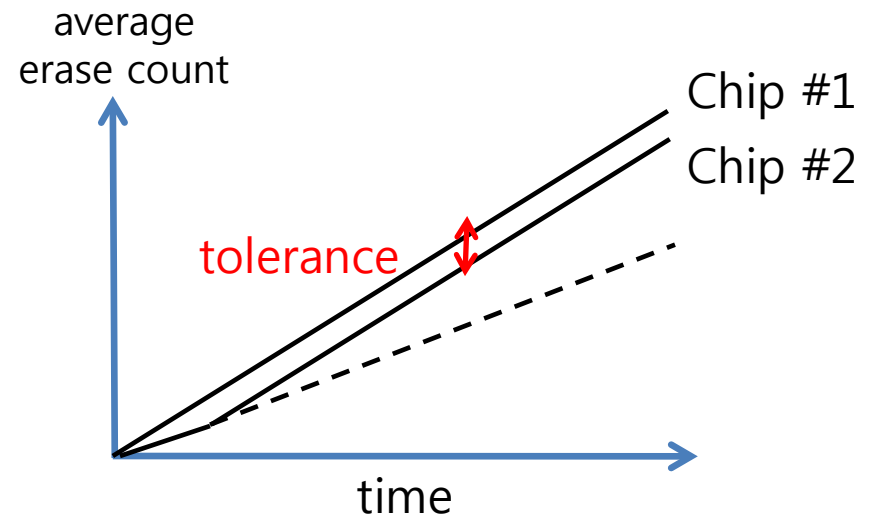
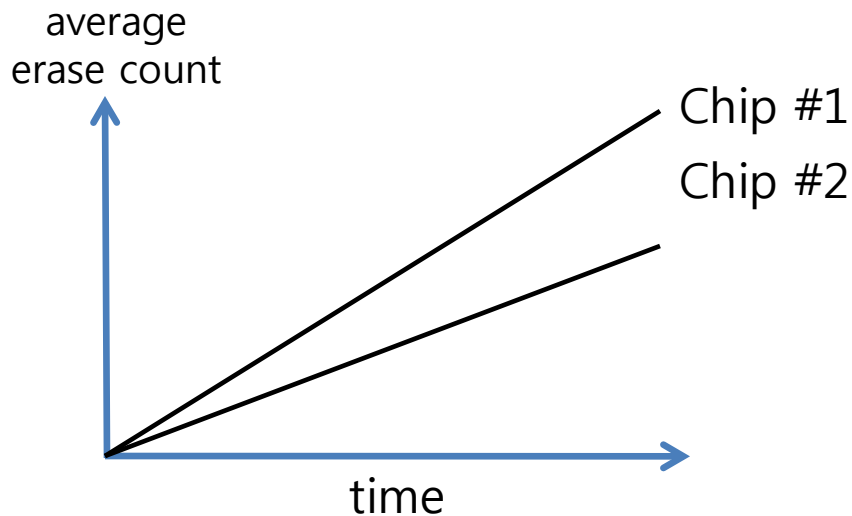
Impact of Over Provisioning

- Over Provision Factor

- $OP = \text{hidden space size} / (\text{hidden space size} + \text{user space size})$
For example, if a 256GB SSD exposes 238GB space to user, $OP = 7\%$.
- Wear Leveling can be done more efficiently by increasing the OP.
- Higher OP alleviates not only Write Amplification, but also Erase Count Variation.
- However, increasing the OP hurts the price advantage of TLC memory.
- **Competence of TLC in terms of performance and life time can be achieved by adjusting OP factor.**

Impact of Global Wear Leveling

- Local Wear Leveling
 - Wear Leveling of each NAND Flash chip is independent of each other.
 - Erase count difference between any two chips cannot be removed.
- Global Wear Leveling
 - All chips participate in Wear Leveling decision at the same time.
 - Cold data can be copied from one chip to another.



Impact of Global Wear Leveling (cont'd)

- Life time improvement of GWL over LWL
 - We can easily derive the improvement rate on two chip model.
 - Improvement rate = $(2 * pe_limit - skew_GWL) / (pe_limit * (1 + skew_LWL))$
skew_LWL = (average erase count of Chip #2) / (average erase count of Chip #1)
skew_GWL = (average erase count of Chip #1) - (average erase count of Chip #2)
pe_limit = PE cycle limit of each chip
Wear acceleration effect is ignored.
- **GWL is less beneficial to 3bit MLC than to 2bit MLC.**
 - Example:
skew_LWL = 90%
skew_GWL = 40 (This can be controlled by tolerance constant.)
when pe_limit = 5000, improvement rate = 1.048 (improved by 4.8%)
when pe_limit = 500, improvement rate = 1.011 (improved by 1.1%)

Miscellaneous Issues

- Performance of SWL
 - Static Wear Leveling involves copying of multiple pages from a block to another.
 - MSB page shows much longer t_{PROG} than CSB/LSB pages.
 - Three read operations and one Joint Page Program operation can be faster than three copy-back operations.
- Delayed block retirement
 - If erase/program failure occurs due to small number of broken bits, we may still use the block to store cold data, rather than discarding it immediately.
- Bad block count variance
 - Variance of bad block count across multiple chips will be higher for TLC, even with well-controlled erase count distribution.
 - In order to cope with it, we need either inter-chip bad block replacement scheme or globally shared block scheme.